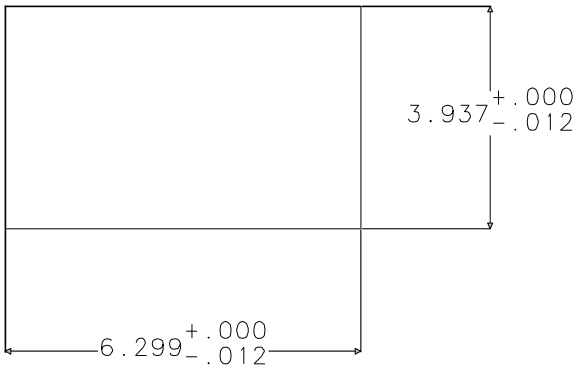

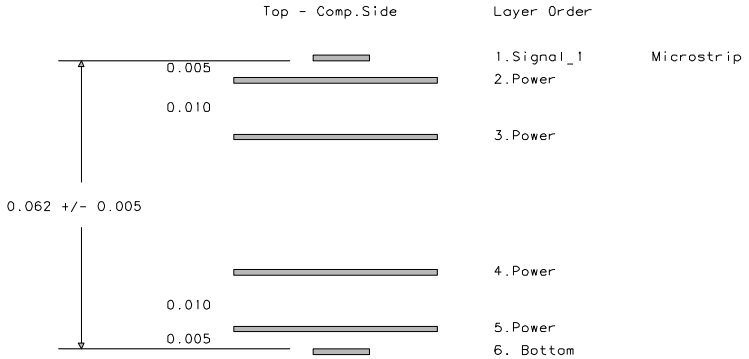

Board Characteristics - 6 LAYER BOARD

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4
2. Minimum trace width and clearence: 0.006"

4. 1 oz copper for all layers.

5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
6. Apply Solder Mask over bare copper.

8. Silkscreen on Component and Solder Sides.

10. FHS tolerances: +/- 0.003 unless specified otherwise.
11. Interlayer spacing as specified

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	830	YES	---	
⊞	.035	8	YES	---	
⌀	.041	70	YES	---	
⊟	.042	20	YES	---	
⊖	.057	8	YES	---	
◫	.098425197	2	YES	---	
⊕	.104	2	YES	---	
□	.106	4	NO	---	
	.15	3	NO	---	
	.2	2	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONS DECIMALS ANGLES
.XX
.XXX
DO NOT SCALE DRAWING

TREATMENT

FINISH

SIMILAR TO | ACT. WT | CALC WT

CONTRACT NO.

APPROVALS	DATE
DRAWN M.Bogdan	10/22/10
CHECKED M.Bogdan	10/22/10
ISSUED	

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE: ASIC Tester Board Specification Drawing

SIZE | FSCM NO. | DWG.NO. 2711 | REV. A

SCALE 1/2 | SHEET

THIS SHEET IS COMPUTER GENERATED